



## JCISE Editorial Board—Year 2024

The *Journal of Computing and Information Science in Engineering (JCISE)* publishes articles related to scientific computing methods (e.g., modeling, simulation, representation, and algorithm) and computational tools (e.g., high-performance computing, virtual and augmented reality) that aim to improve engineering products and systems for their complete lifecycle (e.g., design, manufacturing, operation, maintenance, disposal, and recycling). The interest areas include computer-aided design and manufacturing, computational geometry and geometry processing, cyber-physical-social systems, data analytics and machine learning, engineering optimization, human-computer interface and human modeling, intelligent manufacturing, machine intelligence and robotics system, modeling and simulation and scientific computing, precision engineering and reverse engineering, sustainability and product lifecycle management, and systems engineering and engineering informatics.

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